



GP
ELECTRONICS

GPM070N04NNC

40V N-Channel MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}TYP$	I_D
40V	5.5mΩ@10V	50A
	7.0mΩ@4.5V	

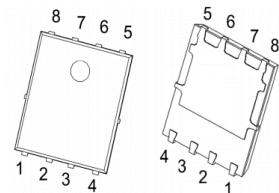
Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

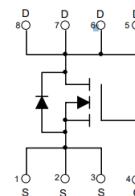
Application

- Power Switching Application

PDFN5x6-8L



Schematic diagram



MARKING:



M070N04N = Device Code

XX = Date Code

Solid Dot = Green Indicator

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	40	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	50	A
Continuous Drain Current ⁶	I_D	20	A
Pulsed Drain Current ²	I_{DM}	180	A
Single Pulsed Avalanche Current ³	I_{AS}	33	A
Single Pulsed Avalanche Energy ³	E_{AS}	280	mJ
Power Dissipation ⁵	P_D	41.6	W
Power Dissipation ⁶	P_D	2.5	W
Thermal Resistance from Junction to Ambient ⁶	$R_{\theta JA}$	55	°C/W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	3	°C/W
Junction Temperature	T_J	-55~+150	°C
Storage Temperature	T_{STG}	-55~+150	°C

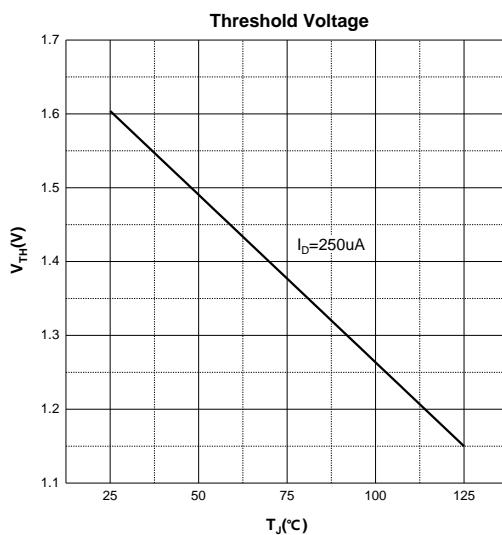
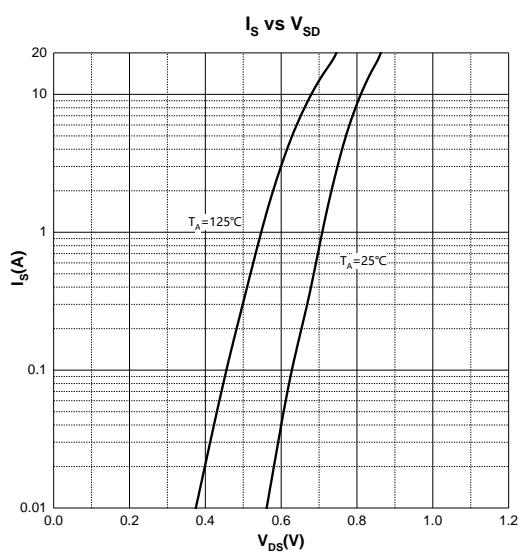
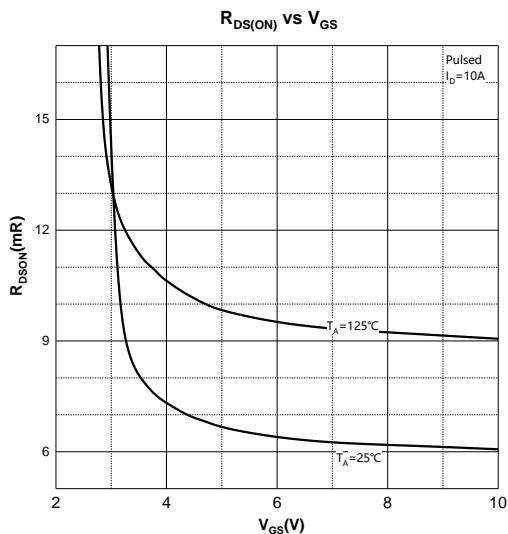
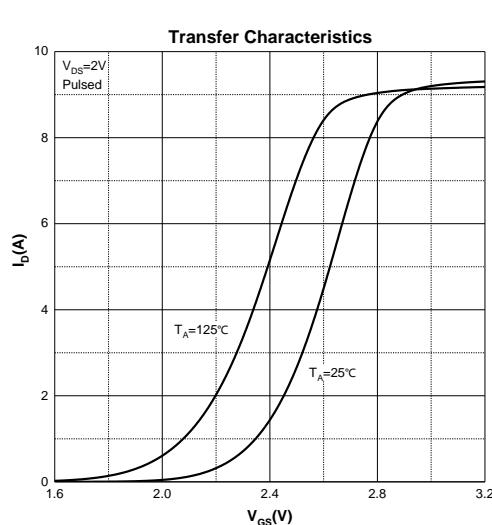
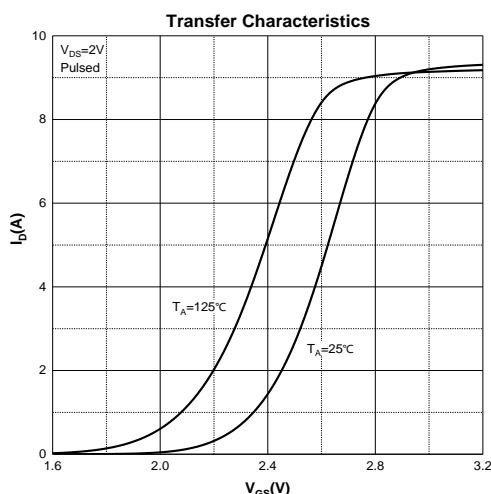
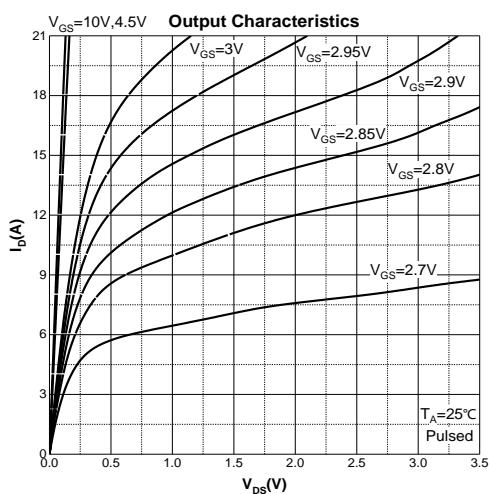
MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

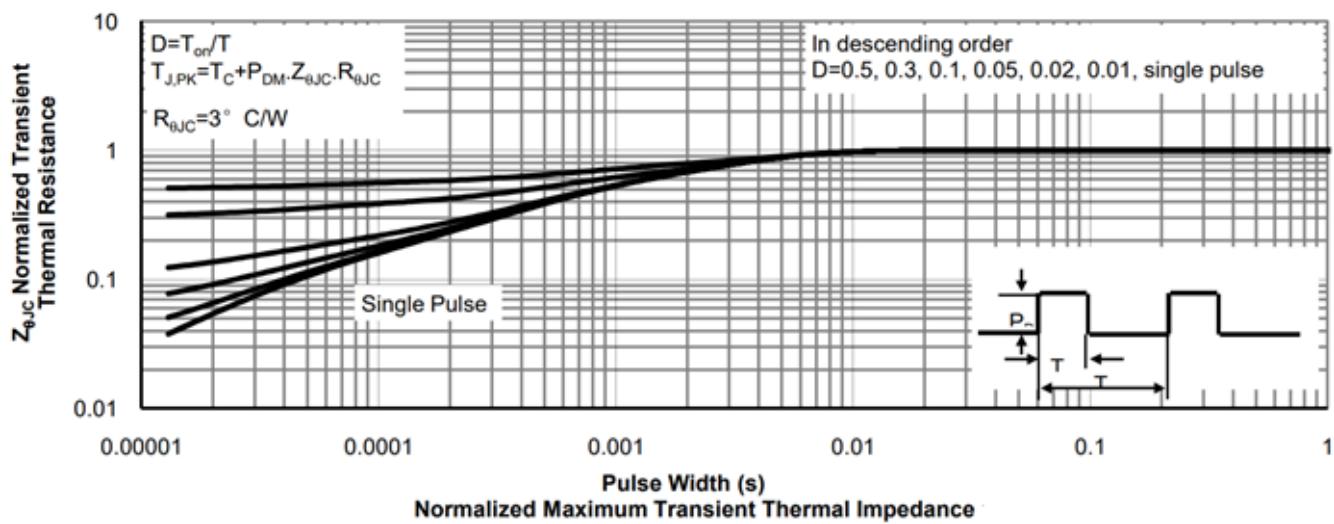
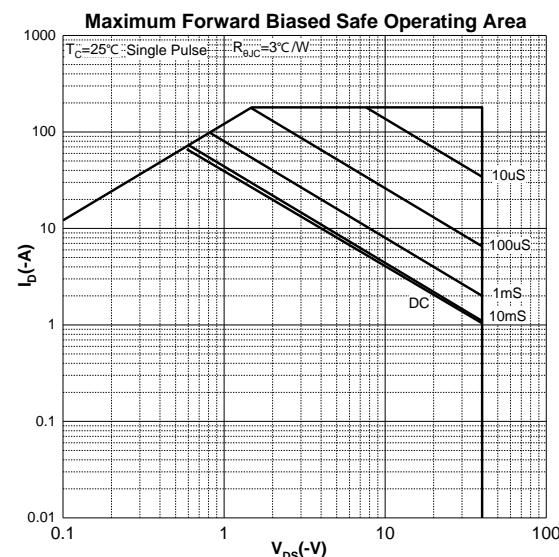
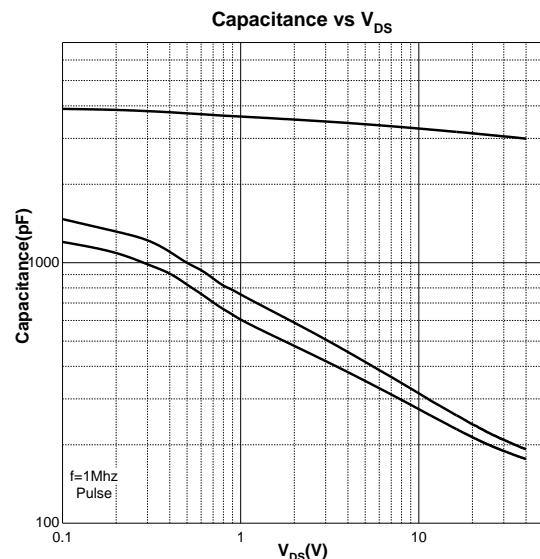
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 32\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			± 100	nA
On Characteristics⁴						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1.2	1.6	2.5	V
Drain-source On-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$		5.5	7.0	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$		7.0	10.5	
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 10\text{V}, I_D = 10\text{A}$		12		S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		3163	3796	pF
Output Capacitance	C_{oss}			240		
Reverse Transfer Capacitance	C_{rss}			214		
Gate Resistance	R_g	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		1.59		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 8\text{A}$		20	26	nC
Gate-source Charge	Q_{gs}			9		
Gate-drain Charge	Q_{gd}			11		
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 15\text{V}, V_{\text{GS}} = 10\text{V}, R_L = 3\Omega, R_G = 3\Omega$		15		ns
Turn-on Rise Time	t_r			5		
Turn-off Delay Ttime	$t_{\text{d}(\text{off})}$			50		
Turn-off Fall Time	t_f			6		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_s = 10\text{A}$			1.2	V

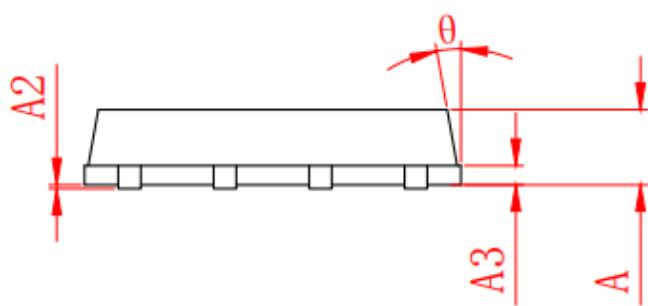
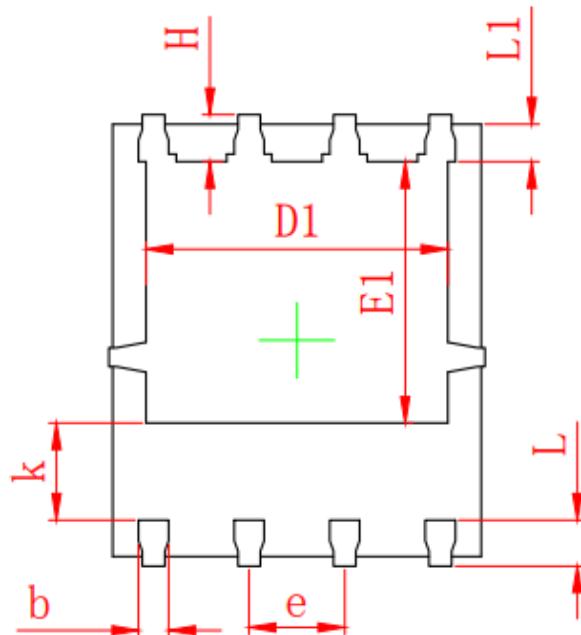
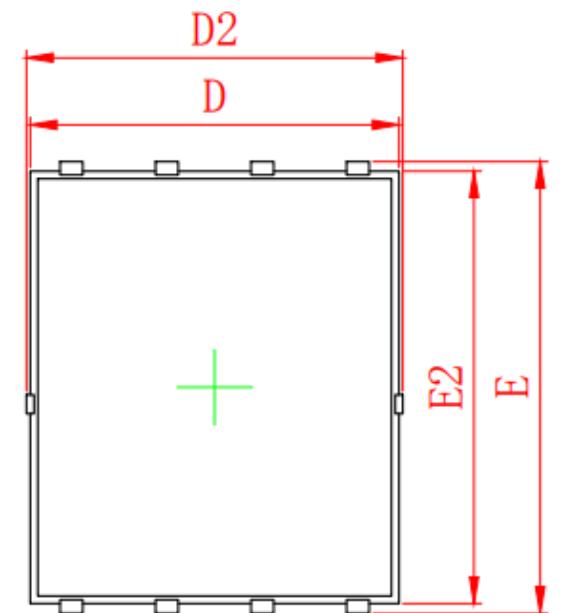
Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
- 3.E_{AS} condition: $V_{\text{DD}} = 25\text{V}, V_{\text{GS}} = 10\text{V}, L = 0.5\text{mH}, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(\text{MAX})} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics





PDFN5x6-8L Package Information


SYMBOL	MILLIMETER	
	MIN	MAX
A	0.900	1.100
A1	0.254	REF.
A2	0~0.05	
D	4.824	4.976
D1	3.910	4.110
D2	4.944	5.076
E	5.924	6.076
E1	3.375	3.575
E2	5.674	5.826
b	0.350	0.450
e	1.270	TYP.
L	0.534	0.686
L1	0.424	0.576
k	1.190	1.390
H	0.549	0.701
θ	8°	12°